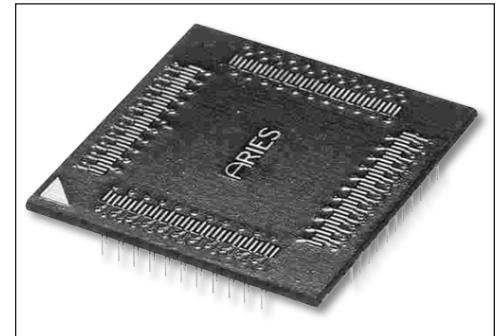




P/N 97-AQ132D 132-Pin Amp Footprint PQFP-to-PGA Socket

FEATURES

- Convert surface-mount PQFP packages to an Amp interstitial PGA footprint.
- Reduce costs by using less-expensive PQFP packages to replace PGA footprints in existing designs.
- Pins are mechanically fastened and soldered to board using Aries patented process, creating a reliable electrical connection and rugged contact.
- Consult factory for Panelized Form or for mounting of consigned chips.



GENERAL SPECIFICATIONS

- BODY MATERIAL: FR-4, 0.062 [1.58] thick, with 1-oz. Cu traces
- PADS: bare Cu protected with ENIG (Immersion Au over Electroless Ni) to eliminate coplanarity concerns and solder bridges associated with hot air solder leveling
- PINS: Brass 360 1/2-hard per UNS C36000, ASTM B16/B16M
- PIN PLATING: Sn/Pb 93/7 per ASTM B579-73 over 100 μ [2.54 μ] Ni per SAE AMS-QQ-N-290
- OPERATING TEMPERATURE: 221°F [105°C]

MOUNTING CONSIDERATIONS

- SUGGESTED PCB HOLE SIZE: 0.028 \pm 0.003 [0.71 \pm 0.08] dia.
- Will plug into existing PGA footprint with matching Pad assignments

CUSTOMIZATION: In addition to the standard products shown on this page, Aries specializes in custom design and production. Special materials, platings, sizes, and configurations can be furnished, depending on the quantity. **NOTE:** Aries reserves the right to change product general specifications without notice.

ORDERING INFORMATION

Specify...

P/N 97-AQ132D or

P/N 97-AQ132D-P for Panelized form

ALL DIMENSIONS: INCHES [MILLIMETERS]

ALL TOLERANCES: \pm 0.005 [0.13] UNLESS OTHERWISE SPECIFIED

ROW-TO-ROW AND PIN-TO-PIN \pm 0.003 [\pm 0.08] NON-CUMULATIVE

CONSULT FACTORY FOR OTHER SIZES AND CONFIGURATIONS

